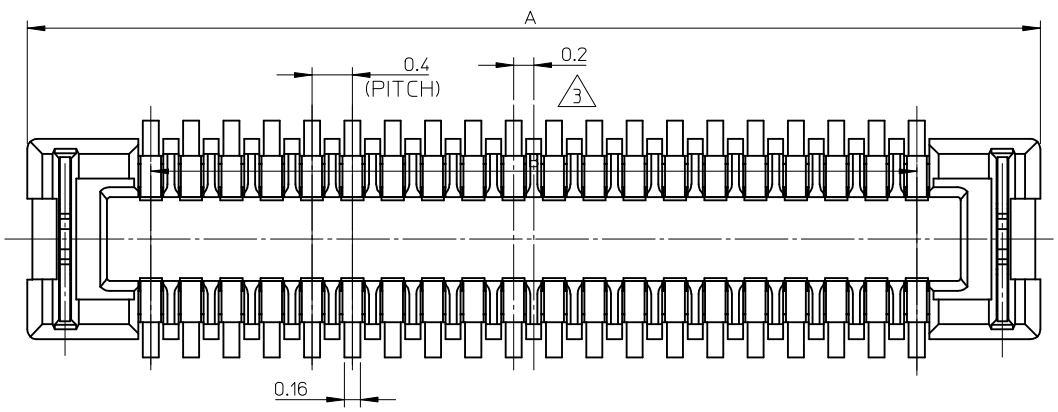
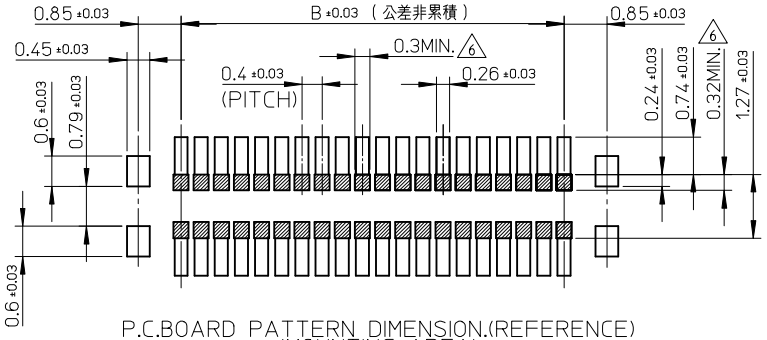
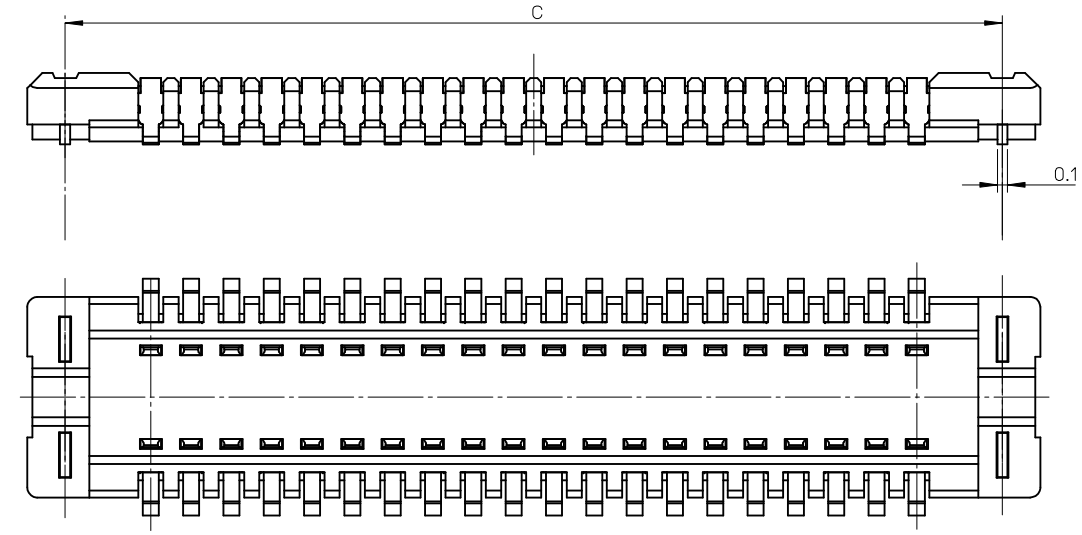
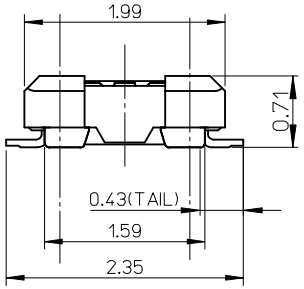




P.C.BOARD PATTERN DIMENSION.(REFERENCE)
(MOUNTING AREA)





C	B	A	EMBOSSED TAPE PACKAGE / ORDER No.	MATERIAL NO.	CIRCUIT
15.3	13.6	16.05	501594-7011	501594-7010	70
12.1	10.4	12.85	501594-5411	501594-5410	54
11.3	9.6	12.05	501594-5011	501594-5010	50
10.1	8.4	10.85	501594-4411	501594-4410	44
9.3	7.6	10.05	501594-4011	501594-4010	40
8.1	6.4	8.85	501594-3411	501594-3410	34
7.3	5.6	8.05	501594-3011	501594-3010	30
6.5	4.8	7.25	501594-2611	501594-2610	26
6.1	4.4	6.85	501594-2411	501594-2410	24
5.7	4.0	6.45	501594-2211	501594-2210	22
5.3	3.6	6.05	501594-2011	501594-2010	20
3.7	2.0	4.45	501594-1211	501594-1210	12
3.3	1.6	4.05	501594-1011	501594-1010	10

REVISED
E C NO: J2008-3370 2008/06/17
DRWN:KSETO 2008/06/17
CH'KD:MSASAO
APPR:MSASAO 2008/06/25
DESCRIPTION
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: T.ASAKAWA DATE: 2006/07/10
CHECKED BY: M.SASAO DATE: 2006/07/10
APPROVED BY: M.SASAO DATE: 2006/07/10

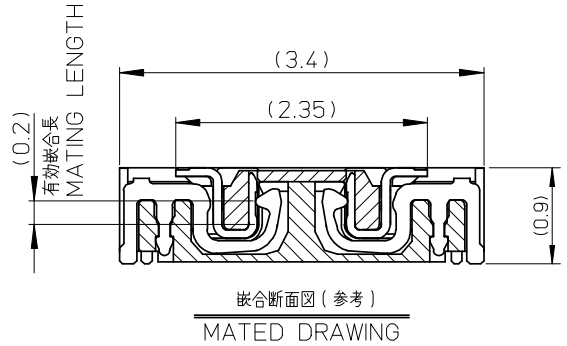
TITLE: 0.4MM PITCH B/B CONN. H=0.9 W=3.4 PLUG ASSY

MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-501594-005
SHEET NO.: 1 OF 2

SIZE A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



嵌合断面図（参考）
MATED DRAWING

注記 NOTES

1.使用材料
MATERIAL

ハウジング：液晶ポリマー（LCP） ガラス充填 UL-94V-0（黒）
HOSING : LIQUID CRYSTAL POLYMER (GLASS FILLED) UL94V-0 (COLOR:BLACK)

ターミナル：りん青銅（t=0.08）
TERMINAL : PHOSHOR BRONZE (t=0.08)

金具 ：りん青銅（t=0.1）
FITTING NAIL : PHOSHOR BRONZE (t=0.1)

2.メッキ仕様
PLATING

ターミナル
TERMINAL

金メッキ 0.1マイクロメートル以上（コンタクト部）
GOLD 0.1 MICROMETER MINIMUM (CONTACT AERA)

金メッキ 0.03マイクロメートル以上（テール部）
GOLD 0.03 MICROMETER MINIMUM (TAIL AERA)

下地メッキ：ニッケルメッキ 1.0 マイクロメートル以上
UNDER PLATING : NICKEL 1.0 MICROMETER MINIMUM

金具
FITTING NAIL

錫メッキ :1.0マイクロメートル以上
TIN PLATING :1.0 MICROMETER MINIMUM

下地メッキ :ニッケル1.0マイクロメートル以上
UNDER PLATING :NICKEL 1.0 MICROMETER MINIMUM

△3 (全極数/2)=偶数の場合に適用
APPLY FOR (CIRCUIT/2)=EVEN

4.嵌合相手 : 501591-**10シリーズ
WITH MATE : 501591-**10SERIES

5.テール及び金具の平坦度は、0.1以下
TAIL AND FITTING NAIL COPLANARITY TO BE 0.1 MAXIMUM

△6 斜線部はパターン書き込み禁止範囲と半田禁止範囲を示す。
ただし、斜線部に同一配線を配置する場合はレジストを施し、この部分に半田は無きこと。
NO PATTERN CIRCUIT AND NO SOLDER ALLOWED IN THE SHADED AREA.
HOWEVER, IF NEEDED TO ADD A TRACE OF THE SAME CIRCUIT, PUT THE SOLDER-RESIST, YET NO SOLDER ALLOWED IN THE AREA.

7.ELV AND RoHS COMPLIANT.

REVISED				DESCRIPTION	REV
EC NO: J2008-3370	DRWN:KSETO	CH'KD:MSASAO	APPR:MSASAO		
2008/06/17	2008/06/17	2008/06/17	2008/06/25		

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE: MM ONLY	SCALE: ---	DESIGN UNITS: METRIC	THIRD ANGLE PROJECTION
DRAWN BY: T.ASAKAWA	DATE: 2006/07/10	TITLE: 0.4MM PITCH B/B CONN. H=0.9 W=3.4 PLUG ASSY	
CHECKED BY: M.SASAO	DATE: 2006/07/10		
APPROVED BY: M.SASAO	DATE: 2006/07/10	molex MOLEX INCORPORATED	
MATERIAL NO.: SEE SHEET 1		DOCUMENT NO.: SD-501594-005	SHEET NO.: 2 OF 2
SIZE: A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		